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Tech ID: 31761

ADDITIONAL TECHNOLOGIES BY THESE INVENTORS

- ▶ Eliminating Misfit Dislocations with In-Situ Compliant Substrate Formation
- ▶ III-Nitride-Based Vertical Cavity Surface Emitting Laser (VCSEL) with a Dielectric P-Side Lens
- ▶ Enhanced Light Extraction LED with a Tunnel Junction Contact Wafer Bonded to a Conductive Oxide
- ▶ Methods to Produce and Recycle Substates for III-Nitride Materials with Electrochemical Etching
- ▶ III-Nitride Tunnel Junction with Modified Interface
- ▶ Improved Reliability & Enhanced Performance of III-Nitride Tunnel Junction Optoelectronic Devices
- ▶ (In,Ga,Al)N Optoelectronic Devices with Thicker Active Layers for Improved Performance
- ▶ Thermally Stable, Laser-Driven White Lighting Device
- ▶ GaN-based Vertical Metal Oxide Semiconductor and Junction Field Effect Transistors
- ▶ Iii-N Transistor With Stepped Cap Layers
- ▶ Novel Multilayer Structure for High-Efficiency UV and Far-UV Light-Emitting Devices
- ▶ A Method To Lift-Off Nitride Materials With Electrochemical Etch
- ▶ Activation of P-Type Layers of Tunnel Junctions in Micro-LEDs
- ▶ High-Intensity Solid State White Laser Diode
- ▶ Nitride Based Ultraviolet LED with an Ultraviolet Transparent Contact
- ▶ Epitaxial Light Control Features in Light Emitting Diodes
- ▶ High-Efficiency Vertical Cavity Surface Emitting Laser Fabrication
- ▶ A Wafer-Scale, Low Defect Density Strain Relaxed Template for III-Nitride-Based High Efficiency and High-Power Devices
- ▶ High-Efficiency and High-Power III-Nitride Devices Grown on or Above a Strain Relaxed Template
- ▶ III-Nitride Based VCSEL with Curved Mirror on P-Side of the Aperture
- ▶ III-N Based Material Structures and Circuit Modules Based on Strain Management